



Full Material Declaration for attached parts list

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Declarations authorised by
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Declaration effective from: 01 May 2009 [Approved: 13 June 2025 12:32 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	2.309%	SILVER, ELEMENTAL	7440-22-4	1.1%
			ALUMINUM, ELEMENTAL	7429-90-5	1.28%
			Silicon	7440-21-3	97.62%
Die attach	Other nonferrous metals	0.203%	4,4'-DIAMINODIPHENYL SULPHONE	80-08-0	1%
			2,2'-(1,4-Butanediylbis(oxyethylene))bisoxirane	2425-79-8	7%
			Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	15%
			Silver	7440-22-4	77%
			Carbon black	1333-86-4	1%
			Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	5%
			Silicon Dioxide	7631-86-9	5%
Encapsulation	EP (Epoxy resin)	62.853%	Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	10%
			Quartz sand	60676-86-0	79%
			PALLADIUM, ELEMENTAL	7440-05-3	3%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.026%	COPPER, ELEMENTAL	7440-50-8	97%
			Tin	7440-31-5	100%
Leadfinish	Tin plating	2.293%			
Leadframe	Copper (e.g. copper amounts in cable harnesses)	32.316%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name
SO-8/SOP (JA) Pb&H-Free [SiAgAl] (CuPd)	Transistor / Regulator